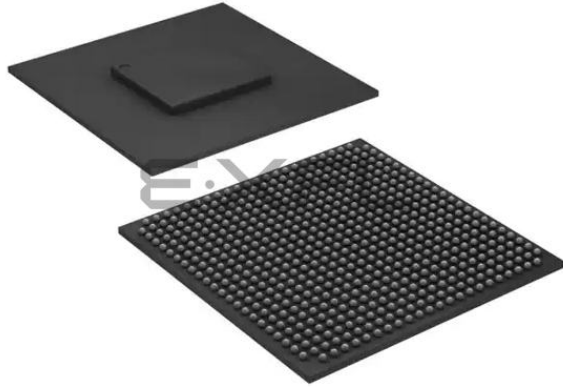




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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	3747
Number of Logic Elements/Cells	89178
Total RAM Bits	6839296
Number of I/O	260
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	572-BGA, FCBGA
Supplier Device Package	572-FBGA, FC (25x25)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep2agx95df25i3n

Table 1–2. Absolute Maximum Ratings for Arria II GZ Devices (Part 2 of 2)

Symbol	Description	Minimum	Maximum	Unit
V _{CCA_L}	Supplies transceiver high voltage power (left side)	-0.5	3.75	V
V _{CCA_R}	Supplies transceiver high voltage power (right side)	-0.5	3.75	V
V _{CCHIP_L}	Supplies transceiver HIP digital power (left side)	-0.5	1.35	V
V _{CCR_L}	Supplies receiver power (left side)	-0.5	1.35	V
V _{CCR_R}	Supplies receiver power (right side)	-0.5	1.35	V
V _{CCT_L}	Supplies transmitter power (left side)	-0.5	1.35	V
V _{CCT_R}	Supplies transmitter power (right side)	-0.5	1.35	V
V _{CCL_GXBLn} (1)	Supplies power to the transceiver PMA TX, PMA RX, and clocking (left side)	-0.5	1.35	V
V _{CCL_GXBRn} (1)	Supplies power to the transceiver PMA TX, PMA RX, and clocking (right side)	-0.5	1.35	V
V _{CCH_GXBLn} (1)	Supplies power to the transceiver PMA output (TX) buffer (left side)	-0.5	1.8	V
V _{CCH_GXBRn} (1)	Supplies power to the transceiver PMA output (TX) buffer (right side)	-0.5	1.8	V
T _J	Operating junction temperature	-55	125	°C
T _{STG}	Storage temperature (no bias)	-65	150	°C

Note to Table 1–2:

(1) n = 0, 1, or 2.

Maximum Allowed Overshoot and Undershoot Voltage

During transitions, input signals may overshoot to the voltage shown in Table 1–3 and undershoot to –2.0 V for magnitude of currents less than 100 mA and periods shorter than 20 ns.

Table 1–3 lists the Arria II GX and GZ maximum allowed input overshoot voltage and the duration of the overshoot voltage as a percentage over the device lifetime. The maximum allowed overshoot duration is specified as a percentage of high-time over the lifetime of the device. A DC signal is equivalent to 100% duty cycle. For example, a signal that overshoots to 4.3 V can only be at 4.3 V for 5.41% over the lifetime of the device; for a device lifetime of 10 years, this amounts to 5.41/10ths of a year.

Table 1–3. Maximum Allowed Overshoot During Transitions for Arria II Devices

Symbol	Description	Condition (V)	Overshoot Duration as % of High Time	Unit
V_I (AC)	AC Input Voltage	4.0	100.000	%
		4.05	79.330	%
		4.1	46.270	%
		4.15	27.030	%
		4.2	15.800	%
		4.25	9.240	%
		4.3	5.410	%
		4.35	3.160	%
		4.4	1.850	%
		4.45	1.080	%
		4.5	0.630	%
		4.55	0.370	%
		4.6	0.220	%

Maximum Allowed I/O Operating Frequency

Table 1–4 lists the maximum allowed I/O operating frequency for Arria II GX I/Os using the specified I/O standards to ensure device reliability.

Table 1–4. Maximum Allowed I/O Operating Frequency for Arria II GX Devices

I/O Standard	I/O Frequency (MHz)
HSTL-18 and HSTL-15	333
SSTL -15	400
SSTL-18	333
2.5-V LVCMOS	260
3.3-V and 3.0-V LVTTTL	250
3.3-V, 3.0-V, 1.8-V, and 1.5-V LVCMOS	
PCI and PCI-X	
SSTL-2	
1.2-V LVCMOS HSTL-12	200

Recommended Operating Conditions

This section lists the functional operation limits for AC and DC parameters for Arria II GX and GZ devices. All supplies are required to monotonically reach their full-rail values without plateaus within t_{RAMP} .

Table 1–5 lists the recommended operating conditions for Arria II GX devices.

Table 1–5. Recommended Operating Conditions for Arria II GX Devices (Note 1) (Part 1 of 2)

Symbol	Description	Condition	Minimum	Typical	Maximum	Unit
V_{CC}	Supplies power to the core, periphery, I/O registers, PCIe HIP block, and transceiver PCS	—	0.87	0.90	0.93	V
V_{CCCB}	Supplies power to the configuration RAM bits	—	1.425	1.50	1.575	V
V_{CCBAT} (2)	Battery back-up power supply for design security volatile key registers	—	1.2	—	3.3	V
V_{CCPD} (3)	Supplies power to the I/O pre-drivers, differential input buffers, and MSEL circuitry	—	3.135	3.3	3.465	V
		—	2.85	3.0	3.15	V
		—	2.375	2.5	2.625	V
V_{CCIO}	Supplies power to the I/O banks (4)	—	3.135	3.3	3.465	V
		—	2.85	3.0	3.15	V
		—	2.375	2.5	2.625	V
		—	1.71	1.8	1.89	V
		—	1.425	1.5	1.575	V
		—	1.14	1.2	1.26	V
V_{CCD_PLL}	Supplies power to the digital portions of the PLL	—	0.87	0.90	0.93	V
V_{CCA_PLL}	Supplies power to the analog portions of the PLL and device-wide power management circuitry	—	2.375	2.5	2.625	V
V_I	DC Input voltage	—	–0.5	—	3.6	V
V_O	Output voltage	—	0	—	V_{CCIO}	V
V_{CCA}	Supplies power to the transceiver PMA regulator	—	2.375	2.5	2.625	V
V_{CCL_GXB}	Supplies power to the transceiver PMA TX, PMA RX, and clocking	—	1.045	1.1	1.155	V
V_{CCH_GXB}	Supplies power to the transceiver PMA output (TX) buffer	—	1.425	1.5	1.575	V
T_J	Operating junction temperature	Commercial	0	—	85	°C
		Industrial	–40	—	100	°C

Table 1-6. Recommended Operating Conditions for Arria II GZ Devices (Note 6) (Part 2 of 2)

Symbol	Description	Condition	Minimum	Typical	Maximum	Unit
V_{CCL_GXBLn} (3)	Transceiver clock power (left side)	—	1.05	1.1	1.15	V
V_{CCL_GXBRn} (3)	Transceiver clock power (right side)	—	1.05	1.1	1.15	V
V_{CCH_GXBLn} (3)	Transmitter output buffer power (left side)	—	1.33/1.425	1.4/1.5 (5)	1.575	V
V_{CCH_GXBRn} (3)	Transmitter output buffer power (right side)	—				
T_J	Operating junction temperature	Commercial	0	—	85	°C
		Industrial	–40	—	100	°C
t_{RAMP}	Power supply ramp time	Normal POR (PORSEL=0)	0.05	—	100	ms
		Fast POR (PORSEL=1)	0.05	—	4	ms

Notes to Table 1-6:

- (1) Altera recommends a 3.0-V nominal battery voltage when connecting V_{CCBAT} to a battery for volatile key backup. If you do not use the volatile security key, you may connect the V_{CCBAT} to either GND or a 3.0-V power supply.
- (2) V_{CCPD} must be 2.5 V when V_{CCIO} is 2.5, 1.8, 1.5, or 1.2 V. V_{CCPD} must be 3.0 V when V_{CCIO} is 3.0 V.
- (3) $n = 0, 1, \text{ or } 2$.
- (4) $V_{CCA_L/R}$ must be connected to a 3.0-V supply if the clock multiplier unit (CMU) phase-locked loop (PLL), receiver clock data recovery (CDR), or both, are configured at a base data rate > 4.25 Gbps. For data rates up to 4.25 Gbps, you can connect $V_{CCA_L/R}$ to either 3.0 V or 2.5 V.
- (5) $V_{CCH_GXBL/R}$ must be connected to a 1.4-V supply if the transmitter channel data rate is > 6.5 Gbps. For data rates up to 6.5 Gbps, you can connect $V_{CCH_GXBL/R}$ to either 1.4 V or 1.5 V.
- (6) Transceiver power supplies do not have power-on-reset (POR) circuitry. After initial power-up, violating the transceiver power supply operating conditions could lead to unpredictable link behavior.

DC Characteristics

This section lists the supply current, I/O pin leakage current, on-chip termination (OCT) accuracy and variation, input pin capacitance, internal weak pull-up and pull-down resistance, hot socketing, and Schmitt trigger input specifications.

Supply Current

Standby current is the current the device draws after the device is configured with no inputs or outputs toggling and no activity in the device. Because these currents vary largely with the resources used, use the Microsoft Excel-based Early Power Estimator (EPE) to get supply current estimates for your design.



For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter.

Table 1-19 lists the weak pull-up resistor values for Arria II GZ devices.

Table 1-19. Internal Weak Pull-Up Resistor for Arria II GZ Devices (Note 1), (2)

Symbol	Description	Conditions	Min	Typ	Max	Unit
R _{PU}	Value of the I/O pin pull-up resistor before and during configuration, as well as user mode if the programmable pull-up resistor option is enabled.	V _{CCIO} = 3.0 V ±5% (3)	—	25	—	kΩ
		V _{CCIO} = 2.5 V ±5% (3)	—	25	—	kΩ
		V _{CCIO} = 1.8 V ±5% (3)	—	25	—	kΩ
		V _{CCIO} = 1.5 V ±5% (3)	—	25	—	kΩ
		V _{CCIO} = 1.2 V ±5% (3)	—	25	—	kΩ

Notes to Table 1-19:

- (1) All I/O pins have an option to enable weak pull-up except configuration, test, and JTAG pins.
- (2) The internal weak pull-down feature is only available for the JTAG TCK pin. The typical value for this internal weak pull-down resistor is approximately 25 kΩ.
- (3) Pin pull-up resistance values may be lower if an external source drives the pin higher than V_{CCIO}.

Hot Socketing

Table 1-20 lists the hot-socketing specification for Arria II GX and GZ devices.

Table 1-20. Hot Socketing Specifications for Arria II Devices

Symbol	Description	Maximum
I _{IOPIN(DC)}	DC current per I/O pin	300 μA
I _{IOPIN(AC)}	AC current per I/O pin	8 mA (1)
I _{XCVRTX(DC)}	DC current per transceiver TX pin	100 mA
I _{XCVRRX(DC)}	DC current per transceiver RX pin	50 mA

Note to Table 1-20:

- (1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, |I_{IOPIN}| = C dv/dt, in which “C” is I/O pin capacitance and “dv/dt” is slew rate.

Schmitt Trigger Input

The Arria II GX device supports Schmitt trigger input on the TDI, TMS, TCK, nSTATUS, nCONFIG, nCE, CONF_DONE, and DCLK pins. A Schmitt trigger feature introduces hysteresis to the input signal for improved noise immunity, especially for signals with slow edge rates.

Table 1-21 lists the hysteresis specifications across the supported V_{CCIO} range for Schmitt trigger inputs in Arria II GX devices.

Table 1-21. Schmitt Trigger Input Hysteresis Specifications for Arria II GX Devices

Symbol	Description	Condition (V)	Minimum	Unit
V _{Schmitt}	Hysteresis for Schmitt trigger input	V _{CCIO} = 3.3	220	mV
		V _{CCIO} = 2.5	180	mV
		V _{CCIO} = 1.8	110	mV
		V _{CCIO} = 1.5	70	mV

Table 1–23. Single-Ended I/O Standards for Arria II GZ Devices (Part 2 of 2)

I/O Standard	V_{CCIO} (V)			V_{IL} (V)		V_{IH} (V)		V_{OL} (V)	V_{OH} (V)	I_{OL} (mA)	I_{OH} (mA)
	Min	Typ	Max	Min	Max	Min	Max	Max	Min		
1.2 V	1.14	1.2	1.26	-0.3	$0.35 \times V_{CCIO}$	$0.65 \times V_{CCIO}$	$V_{CCIO} + 0.3$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	2	-2
3.0-V PCI	2.85	3	3.15	—	$0.3 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	3.6	$0.1 \times V_{CCIO}$	$0.9 \times V_{CCIO}$	1.5	-0.5
3.0-V PCI-X	2.85	3	3.15	—	$0.35 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	—	$0.1 \times V_{CCIO}$	$0.9 \times V_{CCIO}$	1.5	-0.5

Table 1–24 lists the single-ended SSTL and HSTL I/O reference voltage specifications for Arria II GX devices.

Table 1–24. Single-Ended SSTL and HSTL I/O Reference Voltage Specifications for Arria II GX Devices

I/O Standard	V_{CCIO} (V)			V_{REF} (V)			V_{TT} (V)		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	$V_{REF} - 0.04$	V_{REF}	$V_{REF} + 0.04$
SSTL-18 Class I, II	1.71	1.8	1.89	0.833	0.9	0.969	$V_{REF} - 0.04$	V_{REF}	$V_{REF} + 0.04$
SSTL-15 Class I, II	1.425	1.5	1.575	$0.47 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.53 \times V_{CCIO}$	$0.47 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.53 \times V_{CCIO}$
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	0.85	0.9	0.95
HSTL-15 Class I, II	1.425	1.5	1.575	0.71	0.75	0.79	0.71	0.75	0.79
HSTL-12 Class I, II	1.14	1.2	1.26	$0.48 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.52 \times V_{CCIO}$	—	$V_{CCIO}/2$	—

Table 1–25 lists the single-ended SSTL and HSTL I/O reference voltage specifications for Arria II GZ devices.

Table 1–25. Single-Ended SSTL and HSTL I/O Reference Voltage Specifications for Arria II GZ Devices

I/O Standard	V_{CCIO} (V)			V_{REF} (V)			V_{TT} (V)		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	$V_{REF} - 0.04$	V_{REF}	$V_{REF} + 0.04$
SSTL-18 Class I, II	1.71	1.8	1.89	0.833	0.9	0.969	$V_{REF} - 0.04$	V_{REF}	$V_{REF} + 0.04$
SSTL-15 Class I, II	1.425	1.5	1.575	$0.47 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.53 \times V_{CCIO}$	$0.47 \times V_{CCIO}$	V_{REF}	$0.53 \times V_{CCIO}$
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	—	$V_{CCIO}/2$	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9	—	$V_{CCIO}/2$	—
HSTL-12 Class I, II	1.14	1.2	1.26	$0.47 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.53 \times V_{CCIO}$	—	$V_{CCIO}/2$	—

Table 1-26 lists the single-ended SSTL and HSTL I/O standard signal specifications for Arria II GX devices.

Table 1-26. Single-Ended SSTL and HSTL I/O Standard Signal Specifications for Arria II GX Devices

I/O Standard	$V_{IL(DC)} (V)$		$V_{IH(DC)} (V)$		$V_{IL(AC)} (V)$	$V_{IH(AC)} (V)$	$V_{OL} (V)$	$V_{OH} (V)$	$I_{OL} (mA)$	$I_{OH} (mA)$
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-2 Class I	-0.3	$V_{REF} - 0.18$	$V_{REF} + 0.18$	$V_{CCIO} + 0.3$	$V_{REF} - 0.35$	$V_{REF} + 0.35$	$V_{TT} - 0.57$	$V_{TT} + 0.57$	8.1	-8.1
SSTL-2 Class II	-0.3	$V_{REF} - 0.18$	$V_{REF} + 0.18$	$V_{CCIO} + 0.3$	$V_{REF} - 0.35$	$V_{REF} + 0.35$	$V_{TT} - 0.76$	$V_{TT} + 0.76$	16.4	-16.4
SSTL-18 Class I	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCIO} + 0.3$	$V_{REF} - 0.25$	$V_{REF} + 0.25$	$V_{TT} - 0.475$	$V_{TT} + 0.475$	6.7	-6.7
SSTL-18 Class II	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCIO} + 0.3$	$V_{REF} - 0.25$	$V_{REF} + 0.25$	0.28	$V_{CCIO} - 0.28$	13.4	-13.4
SSTL-15 Class I	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCIO} + 0.3$	$V_{REF} - 0.175$	$V_{REF} + 0.175$	$0.2 \times V_{CCIO}$	$0.8 \times V_{CCIO}$	8	-8
SSTL-15 Class II	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCIO} + 0.3$	$V_{REF} - 0.175$	$V_{REF} + 0.175$	$0.2 \times V_{CCIO}$	$0.8 \times V_{CCIO}$	16	-16
HSTL-18 Class I	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCIO} + 0.3$	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	8	-8
HSTL-18 Class II	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCIO} + 0.3$	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	16	-16
HSTL-15 Class I	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCIO} + 0.3$	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	8	-8
HSTL-15 Class II	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCIO} + 0.3$	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	16	-16
HSTL-12 Class I	-0.15	$V_{REF} - 0.08$	$V_{REF} + 0.08$	$V_{CCIO} + 0.15$	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	8	-8
HSTL-12 Class II	-0.15	$V_{REF} - 0.08$	$V_{REF} + 0.08$	$V_{CCIO} + 0.15$	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	14	-14

Table 1-27 lists the single-ended SSTL and HSTL I/O standard signal specifications for Arria II GZ devices.

Table 1-27. Single-Ended SSTL and HSTL I/O Standards Signal Specifications for Arria II GZ Devices (Part 1 of 2)

I/O Standard	$V_{IL(DC)} (V)$		$V_{IH(DC)} (V)$		$V_{IL(AC)} (V)$	$V_{IH(AC)} (V)$	$V_{OL} (V)$	$V_{OH} (V)$	$I_{OL} (mA)$	$I_{OH} (mA)$
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-2 Class I	-0.3	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$V_{CCIO} + 0.3$	$V_{REF} - 0.31$	$V_{REF} + 0.31$	$V_{TT} - 0.57$	$V_{TT} + 0.57$	8.1	-8.1
SSTL-2 Class II	-0.3	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$V_{CCIO} + 0.3$	$V_{REF} - 0.31$	$V_{REF} + 0.31$	$V_{TT} - 0.76$	$V_{TT} + 0.76$	16.2	-16.2
SSTL-18 Class I	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCIO} + 0.3$	$V_{REF} - 0.25$	$V_{REF} + 0.25$	$V_{TT} - 0.475$	$V_{TT} + 0.475$	6.7	-6.7
SSTL-18 Class II	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCIO} + 0.3$	$V_{REF} - 0.25$	$V_{REF} + 0.25$	0.28	$V_{CCIO} - 0.28$	13.4	-13.4
SSTL-15 Class I	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.175$	$V_{REF} + 0.175$	$0.2 \times V_{CCIO}$	$0.8 \times V_{CCIO}$	8	-8

Table 1-30 lists the HSTL I/O standards for Arria II GX devices.

Table 1-30. Differential HSTL I/O Standards for Arria II GX Devices

I/O Standard	V _{CCIO} (V)			V _{DIF(DC)} (V)		V _{X(AC)} (V)			V _{CM(DC)} (V)			V _{DIF(AC)} (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Typ	Max	Min	Max
HSTL-18 Class I	1.71	1.8	1.89	0.2	—	0.85	—	0.95	0.88	—	0.95	0.4	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.2	—	0.71	—	0.79	0.71	—	0.79	0.4	—
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	—	—	0.5 × V _{CCIO}	—	0.48 × V _{CCIO}	0.5 × V _{CCIO}	0.52 × V _{CCIO}	0.3	—

Table 1-31 lists the HSTL I/O standards for Arria II GZ devices.

Table 1-31. Differential HSTL I/O Standards for Arria II GZ Devices

I/O Standard	V _{CCIO} (V)			V _{DIF(DC)} (V)		V _{X(AC)} (V)			V _{CM(DC)} (V)			V _{DIF(AC)} (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Typ	Max	Min	Max
HSTL-18 Class I	1.71	1.8	1.89	0.2	—	0.78	—	1.12	0.78	—	1.12	0.4	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.2	—	0.68	—	0.9	0.68	—	0.9	0.4	—
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	V _{CCIO} + 0.3	—	0.5 × V _{CCIO}	—	0.4 × V _{CCIO}	0.5 × V _{CCIO}	0.6 × V _{CCIO}	0.3	V _{CCIO} + 0.48

Table 1-32 lists the differential I/O standard specifications for Arria II GX devices.

Table 1-32. Differential I/O Standard Specifications for Arria II GX Devices (Note 1)

I/O Standard	V _{CCIO} (V)			V _{ID} (mV)			V _{ICM} (V) (2)		V _{OD} (V) (3)			V _{OCM} (V)		
	Min	Typ	Max	Min	Cond.	Max	Min	Max	Min	Typ	Max	Min	Typ	Max
2.5 V LVDS	2.375	2.5	2.625	100	V _{CM} = 1.25 V	—	0.05	1.80	0.247	—	0.6	1.125	1.25	1.375
RSDS (4)	2.375	2.5	2.625	—	—	—	—	—	0.1	0.2	0.6	0.5	1.2	1.4
Mini-LVDS (4)	2.375	2.5	2.625	—	—	—	—	—	0.25	—	0.6	1	1.2	1.4
LVPECL (5)	2.375	2.5	2.625	300	—	—	0.6	1.8	—	—	—	—	—	—
BLVDS (6)	2.375	2.5	2.625	100	—	—	—	—	—	—	—	—	—	—

Notes to Table 1-32:

- (1) The 1.5 V PCML transceiver I/O standard specifications are described in “Transceiver Performance Specifications” on page 1-21.
- (2) V_{IN} range: 0 ≤ V_{IN} ≤ 1.85 V.
- (3) R_L range: 90 ≤ R_L ≤ 110 Ω.
- (4) The RSDS and mini-LVDS I/O standards are only supported for differential outputs.
- (5) The LVPECL input standard is supported at the dedicated clock input pins (GCLK) only.
- (6) There are no fixed V_{ICM}, V_{OD}, and V_{OCM} specifications for BLVDS. These specifications depend on the system topology.

Switching Characteristics

This section provides performance characteristics of the Arria II GX and GZ core and periphery blocks for commercial grade devices. The following tables are considered final and are based on actual silicon characterization and testing. These numbers reflect the actual performance of the device under worst-case silicon process, voltage, and junction temperature conditions.

Transceiver Performance Specifications

Table 1–34 lists the Arria II GX transceiver specifications.

Table 1–34. Transceiver Specifications for Arria II GX Devices (Note 1) (Part 1 of 7)

Symbol/ Description	Condition	I3			C4			C5 and I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Reference Clock														
Supported I/O Standards	1.2-V PCML, 1.5-V PCML, 2.5-V PCML, Differential LVPECL, LVDS, and HCSL													
Input frequency from REFCLK input pins	—	50	—	622.08	50	—	622.08	50	—	622.08	50	—	622.08	MHz
Input frequency from PLD input	—	50	—	200	50	—	200	50	—	200	50	—	200	MHz
Absolute V _{MAX} for a REFCLK pin	—	—	—	2.2	—	—	2.2	—	—	2.2	—	—	2.2	V
Absolute V _{MIN} for a REFCLK pin	—	−0.3	—	—	−0.3	—	—	−0.3	—	—	−0.3	—	—	V
Rise/fall time (2)	—	—	—	0.2	—	—	0.2	—	—	0.2	—	—	0.2	UI
Duty cycle	—	45	—	55	45	—	55	45	—	55	45	—	55	%
Peak-to-peak differential input voltage	—	200	—	2000	200	—	2000	200	—	2000	200	—	2000	mV
Spread-spectrum modulating clock frequency	PCIe	30	—	33	30	—	33	30	—	33	30	—	33	kHz

Table 1–34. Transceiver Specifications for Arria II GX Devices (Note 1) (Part 2 of 7)

Symbol/ Description	Condition	I3			C4			C5 and I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Spread-spectrum downspread	PCIe	—	0 to –0.5%	—	—	0 to –0.5%	—	—	0 to –0.5%	—	—	0 to –0.5%	—	—
On-chip termination resistors	—	—	100	—	—	100	—	—	100	—	—	100	—	Ω
V _{ICM} (AC coupled)	—	1100 ± 5%			1100 ± 5%			1100 ± 5%			1100 ± 5%			mV
V _{ICM} (DC coupled)	HCSL I/O standard for PCIe reference clock	250	—	550	250	—	550	250	—	550	250	—	550	mV
Transmitter REFCLK Phase Noise	10 Hz	—	—	-50	—	—	-50	—	—	-50	—	—	-50	dBc/Hz
	100 Hz	—	—	-80	—	—	-80	—	—	-80	—	—	-80	dBc/Hz
	1 KHz	—	—	-110	—	—	-110	—	—	-110	—	—	-110	dBc/Hz
	10 KHz	—	—	-120	—	—	-120	—	—	-120	—	—	-120	dBc/Hz
	100 KHz	—	—	-120	—	—	-120	—	—	-120	—	—	-120	dBc/Hz
	≥ 1 MHz	—	—	-130	—	—	-130	—	—	-130	—	—	-130	dBc/Hz
Transmitter REFCLK Phase Jitter (rms) for 100 MHz REFCLK (3)	10 KHz to 20 MHz	—	—	3	—	—	3	—	—	3	—	—	3	ps
R _{ref}	—	—	2000 ± 1%	—	—	2000 ± 1%	—	—	2000 ± 1%	—	—	2000 ± 1%	—	Ω
Transceiver Clocks														
Calibration block clock frequency (cal_blk_clk)	—	10	—	125	10	—	125	10	—	125	10	—	125	MHz

Table 1–35. Transceiver Specifications for Arria II GZ Devices (Part 3 of 5)

Symbol/ Description	Conditions	–C3 and –I3 (1)			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Receiver DC Coupling Support	—	For more information about receiver DC coupling support, refer to the “DC-Coupled Links” section in the <i>Transceiver Architecture for Arria II Devices</i> chapter.						
Differential on-chip termination resistors	85–Ω setting	85 ± 20%			85 ± 20%			Ω
	100–Ω setting	100 ± 20%			100 ± 20%			Ω
	120–Ω setting	120 ± 20%			120 ± 20%			Ω
	150–Ω setting	150 ± 20%			150 ± 20%			Ω
Differential and common mode return loss	PCIe (Gen 1 and Gen 2), XAUI, HiGig+, CEI SR/LR, SRIO SR/LR, CPRI LV/HV, OBSAI, SATA	Compliant						—
Programmable PPM detector (9)	—	± 62.5, 100, 125, 200, 250, 300, 500, 1,000						ppm
Run length	—	—	—	200	—	—	200	UI
Programmable equalization	—	—	—	16	—	—	16	dB
t _{LTR} (10)	—	—	—	75	—	—	75	μs
t _{LTR_LTD_Manual} (11)	—	15	—	—	15	—	—	μs
t _{LTD_Manual} (12)	—	—	—	4000	—	—	4000	ns
t _{LTD_Auto} (13)	—	—	—	4000	—	—	4000	ns
Receiver CDR 3 dB Bandwidth in lock-to-data (LTD) mode	PCIe Gen1	2.0 - 3.5						MHz
	PCIe Gen2	40 - 65						MHz
	(OIF) CEI PHY at 6.375 Gbps	20 - 35						MHz
	XAUI	10 - 18						MHz
	SRIO 1.25 Gbps	10 - 18						MHz
	SRIO 2.5 Gbps	10 - 18						MHz
	SRIO 3.125 Gbps	6 - 10						MHz
	GIGE	6 - 10						MHz
	SONET OC12	3 - 6						MHz
	SONET OC48	14 - 19						MHz
Receiver buffer and CDR offset cancellation time (per channel)	—	—	—	17000	—	—	17000	recon fig_ clk cycles
Programmable DC gain	DC Gain Setting = 0	—	0	—	—	0	—	dB
	DC Gain Setting = 1	—	3	—	—	3	—	dB
	DC Gain Setting = 2	—	6	—	—	6	—	dB

Figure 1-1 shows the lock time parameters in manual mode.

 LTD = lock-to-data. LTR = lock-to-reference.

Figure 1-1. Lock Time Parameters for Manual Mode

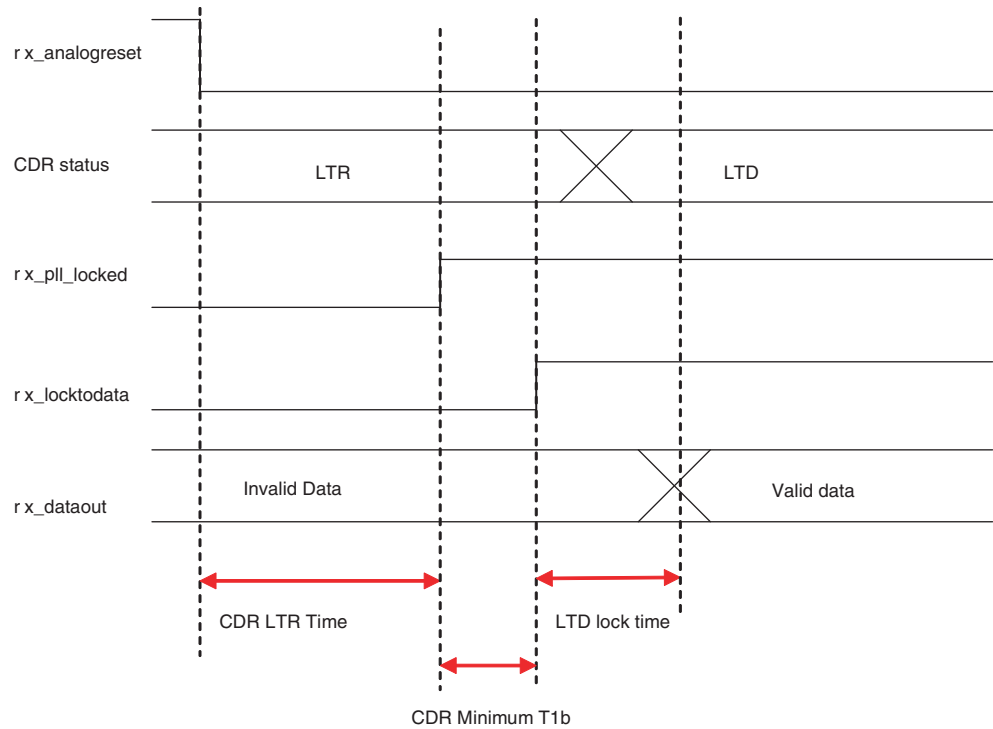


Figure 1-2 shows the lock time parameters in automatic mode.

Figure 1-2. Lock Time Parameters for Automatic Mode

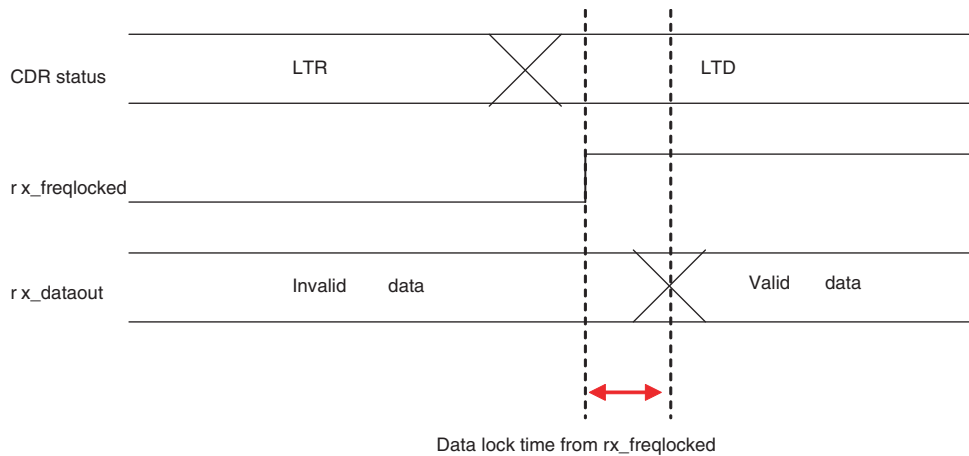


Table 1–39. Transmitter Pre-Emphasis Levels for Arria II GZ Devices (Part 2 of 2)

Pre-Emphasis 1st Post-Tap Setting	V _{DD} Setting							
	0	1	2	3	4	5	6	7
29	N/A	N/A	N/A	12.5	9.6	7.7	6.3	4.3
30	N/A	N/A	N/A	N/A	11.4	9	7.4	N/A
31	N/A	N/A	N/A	N/A	12.9	10	8.2	N/A

Table 1–40 lists the transceiver jitter specifications for all supported protocols for Arria II GX devices.

Table 1–40. Transceiver Block Jitter Specifications for Arria II GX Devices (Note 1) (Part 1 of 10)

Symbol/ Description	Conditions	I3			C4			C5, I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
SONET/SDH Transmit Jitter Generation (2)														
Peak-to-peak jitter at 622.08 Mbps	Pattern = PRBS15	—	—	0.1	—	—	0.1	—	—	0.1	—	—	0.1	UI
RMS jitter at 622.08 Mbps	Pattern = PRBS15	—	—	0.01	—	—	0.01	—	—	0.01	—	—	0.01	UI
Peak-to-peak jitter at 2488.32 Mbps	Pattern = PRBS15	—	—	0.1	—	—	0.1	—	—	0.1	—	—	0.1	UI
RMS jitter at 2488.32 Mbps	Pattern = PRBS15	—	—	0.01	—	—	0.01	—	—	0.01	—	—	0.01	UI
SONET/SDH Receiver Jitter Tolerance (2)														
Jitter tolerance at 622.08 Mbps	Jitter frequency = 0.03 KHz Pattern = PRBS15	> 15			> 15			> 15			> 15			UI
	Jitter frequency = 25 KHZ Pattern = PRBS15	> 1.5			> 1.5			> 1.5			> 1.5			UI
	Jitter frequency = 250 KHz Pattern = PRBS15	> 0.15			> 0.15			> 0.15			> 0.15			UI

Table 1–40. Transceiver Block Jitter Specifications for Arria II GX Devices (Note 1) (Part 4 of 10)

Symbol/ Description	Conditions	I3			C4			C5, I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Total jitter (peak-to-peak)	Pattern = CRPAT	—	—	0.27 9	—	—	0.279	—	—	0.279	—	—	0.279	UI
GIGE Receiver Jitter Tolerance (6)														
Deterministic jitter tolerance (peak-to-peak)	Pattern = CJPAT	> 0.4			> 0.4			> 0.4			> 0.4			UI
Combined deterministic and random jitter tolerance (peak-to-peak)	Pattern = CJPAT	> 0.66			> 0.66			> 0.66			> 0.66			UI
HiGig Transmit Jitter Generation (7)														
Deterministic jitter (peak-to-peak)	Data rate = 3.75 Gbps Pattern = CJPAT	—	—	0.17	—	—	0.17	—	—	—	—	—	—	UI
Total jitter (peak-to-peak)	Data rate = 3.75 Gbps Pattern = CJPAT	—	—	0.35	—	—	0.35	—	—	—	—	—	—	UI
HiGig Receiver Jitter Tolerance (7)														
Deterministic jitter tolerance (peak-to-peak)	Data rate = 3.75 Gbps Pattern = CJPAT	> 0.37			> 0.37			—	—	—	—	—	—	UI
Combined deterministic and random jitter tolerance (peak-to-peak)	Data rate = 3.75 Gbps Pattern = CJPAT	> 0.65			> 0.65			—	—	—	—	—	—	UI
Sinusoidal jitter tolerance (peak-to-peak)	Jitter frequency = 22.1 KHz Data rate = 3.75 Gbps Pattern = CJPAT	> 8.5			> 8.5			—	—	—	—	—	—	UI
	Jitter frequency = 1.875MHz Data rate = 3.75 Gbps Pattern = CJPAT	> 0.1			> 0.1			—	—	—	—	—	—	UI
	Jitter frequency = 20 MHz Data rate = 3.75 Gbps Pattern = CJPAT	> 0.1			> 0.1			—	—	—	—	—	—	UI

Table 1–40. Transceiver Block Jitter Specifications for Arria II GX Devices (Note 1) (Part 5 of 10)

Symbol/ Description	Conditions	I3			C4			C5, I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
SDI Transmitter Jitter Generation (8)														
Alignment jitter (peak-to-peak)	Data rate = 1.485 Gbps (HD) pattern = Color Bar Low- frequency Roll-off = 100 KHz	0.2	—	—	0.2	—	—	0.2	—	—	0.2	—	—	UI
	Data rate = 2.97 Gbps (3G) pattern = Color bar Low- frequency Roll-off = 100 KHz	0.3	—	—	0.3	—	—	0.3	—	—	0.3	—	—	UI
SDI Receiver Jitter Tolerance (8)														
Sinusoidal jitter tolerance (peak-to-peak)	Jitter frequency = 15 KHz Data rate = 2.97 Gbps (3G) Pattern = single line scramble color bar	> 2			> 2			> 2			> 2			UI
	Jitter frequency = 100 KHz Data rate = 2.97 Gbps (3G) Pattern = single line scramble color bar	> 0.3			> 0.3			> 0.3			> 0.3			UI
	Jitter frequency = 148.5 MHz Data rate = 2.97 Gbps (3G) Pattern = single line scramble color bar	> 0.3			> 0.3			> 0.3			> 0.3			UI

Table 1–40. Transceiver Block Jitter Specifications for Arria II GX Devices (Note 1) (Part 8 of 10)

Symbol/ Description	Conditions	I3			C4			C5, I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
CPRI Transmit Jitter Generation (11)														
Total jitter	E.6.HV, E.12.HV Pattern = CJPAT	—	—	0.27 9	—	—	0.279	—	—	0.279	—	—	0.279	UI
	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJTPAT	—	—	0.35	—	—	0.35	—	—	0.35	—	—	0.35	UI
Deterministic jitter	E.6.HV, E.12.HV Pattern = CJPAT	—	—	0.14	—	—	0.14	—	—	0.14	—	—	0.14	UI
	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJTPAT	—	—	0.17	—	—	0.17	—	—	0.17	—	—	0.17	UI
CPRI Receiver Jitter Tolerance (11)														
Total jitter tolerance	E.6.HV, E.12.HV Pattern = CJPAT	> 0.66			> 0.66			> 0.66			> 0.66			UI
Deterministic jitter tolerance	E.6.HV, E.12.HV Pattern = CJPAT	> 0.4			> 0.4			> 0.4			> 0.4			UI
Total jitter tolerance	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJTPAT	> 0.65			> 0.65			> 0.65			> 0.65			UI
	E.60.LV Pattern = PRBS31	> 0.6			—			—			—			UI
Deterministic jitter tolerance	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJTPAT	> 0.37			> 0.37			> 0.37			> 0.37			UI
	E.60.LV Pattern = PRBS31	> 0.45			—			—			—			UI
Combined deterministic and random jitter tolerance	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJTPAT	> 0.55			> 0.55			> 0.55			> 0.55			UI
OBSAI Transmit Jitter Generation (12)														
Total jitter at 768 Mbps, 1536 Mbps, and 3072 Mbps	REFCLK = 153.6 MHz Pattern = CJPAT	—	—	0.35	—	—	0.35	—	—	0.35	—	—	0.35	UI
Deterministic jitter at 768 Mbps, 1536 Mbps, and 3072 Mbps	REFCLK = 153.6 MHz Pattern = CJPAT	—	—	0.17	—	—	0.17	—	—	0.17	—	—	0.17	UI

Table 1–40. Transceiver Block Jitter Specifications for Arria II GX Devices (Note 1) (Part 9 of 10)

Symbol/ Description	Conditions	I3			C4			C5, I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
OBSAI Receiver Jitter Tolerance (12)														
Deterministic jitter tolerance at 768 Mbps, 1536 Mbps, and 3072 Mbps	Pattern = CJPAT	> 0.37			> 0.37			> 0.37			> 0.37			UI
Combined deterministic and random jitter tolerance at 768 Mbps, 1536 Mbps, and 3072 Mbps	Pattern = CJPAT	> 0.55			> 0.55			> 0.55			> 0.55			UI
Sinusoidal jitter tolerance at 768 Mbps	Jitter frequency = 5.4 KHz Pattern = CJPAT	> 8.5			> 8.5			> 8.5			> 8.5			UI
	Jitter frequency = 460.8 KHz to 20 MHz Pattern = CJPAT	> 0.1			> 0.1			> 0.1			> 0.1			UI
Sinusoidal jitter tolerance at 1536 Mbps	Jitter frequency = 10.9 KHz Pattern = CJPAT	> 8.5			> 8.5			> 8.5			> 8.5			UI
	Jitter frequency = 921.6 KHz to 20 MHz Pattern = CJPAT	> 0.1			> 0.1			> 0.1			> 0.1			UI

Table 1-45. PLL Specifications for Arria II GZ Devices (Part 2 of 2)

Symbol	Parameter	Min	Typ	Max	Unit
t_{DLOCK}	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)	—	—	1	ms
f_{CLBW}	PLL closed-loop low bandwidth	—	0.3	—	MHz
	PLL closed-loop medium bandwidth	—	1.5	—	MHz
	PLL closed-loop high bandwidth (7)	—	4	—	MHz
$t_{\text{PLL_PSERR}}$	Accuracy of PLL phase shift	—	—	±50	ps
t_{ARESET}	Minimum pulse width on the areset signal	10	—	—	ns
t_{INCCJ} (3), (4)	Input clock cycle to cycle jitter ($F_{\text{REF}} \geq 100$ MHz)	—	—	0.15	UI (p-p)
	Input clock cycle to cycle jitter ($F_{\text{REF}} < 100$ MHz)	—	—	±750	ps (p-p)
$t_{\text{OUTPJ_DC}}$ (5)	Period Jitter for dedicated clock output ($F_{\text{OUT}} \geq 100$ MHz)	—	—	175	ps (p-p)
	Period Jitter for dedicated clock output ($F_{\text{OUT}} < 100$ MHz)	—	—	17.5	mUI (p-p)
$t_{\text{OUTCCJ_DC}}$ (5)	Cycle to Cycle Jitter for dedicated clock output ($F_{\text{OUT}} \geq 100$ MHz)	—	—	175	ps (p-p)
	Cycle to Cycle Jitter for dedicated clock output ($F_{\text{OUT}} < 100$ MHz)	—	—	17.5	mUI (p-p)
$t_{\text{OUTPJ_IO}}$ (5), (8)	Period Jitter for clock output on regular I/O ($F_{\text{OUT}} \geq 100$ MHz)	—	—	600	ps (p-p)
	Period Jitter for clock output on regular I/O ($F_{\text{OUT}} < 100$ MHz)	—	—	60	mUI (p-p)
$t_{\text{OUTCCJ_IO}}$ (5), (8)	Cycle to Cycle Jitter for clock output on regular I/O ($F_{\text{OUT}} \geq 100$ MHz)	—	—	600	ps (p-p)
	Cycle to Cycle Jitter for clock output on regular I/O ($F_{\text{OUT}} < 100$ MHz)	—	—	60	mUI (p-p)
$t_{\text{CASC_OUTPJ_DC}}$ (5), (6)	Period Jitter for dedicated clock output in cascaded PLLs ($F_{\text{OUT}} \geq 100$ MHz)	—	—	250	ps (p-p)
	Period Jitter for dedicated clock output in cascaded PLLs ($F_{\text{OUT}} < 100$ MHz)	—	—	25	mUI (p-p)
f_{DRIFT}	Frequency drift after PFDENA is disabled for duration of 100 μ s	—	—	±10	%

Notes to Table 1-45:

- (1) This specification is limited in the Quartus II software by the I/O maximum frequency. The maximum I/O frequency is different for each I/O standard.
- (2) This specification is limited by the lower of the two: I/O F_{MAX} or F_{OUT} of the PLL.
- (3) A high input jitter directly affects the PLL output jitter. To have low PLL output clock jitter, you must provide a clean clock source that is less than 120 ps.
- (4) F_{REF} is f_{IN}/N when $N = 1$.
- (5) Peak-to-peak jitter with a probability level of 10^{-12} (14 sigma, 99.9999999974404% confidence level). The output jitter specification applies to the intrinsic jitter of the PLL, when an input jitter of 30 ps is applied. The external memory interface clock output jitter specifications use a different measurement method and are available in [Table 1-64 on page 1-71](#).
- (6) The cascaded PLL specification is only applicable with the following condition:
 - a. Upstream PLL: $0.59 \text{ MHz} \leq \text{Upstream PLL BW} < 1 \text{ MHz}$
 - b. Downstream PLL: $\text{Downstream PLL BW} > 2 \text{ MHz}$
- (7) High bandwidth PLL settings are not supported in external feedback mode.
- (8) External memory interface clock output jitter specifications use a different measurement method, which is available in [Table 1-63 on page 1-71](#).

Periphery Performance

This section describes periphery performance, including high-speed I/O, external memory interface, and IOE programmable delay.

I/O performance supports several system interfaces, for example the high-speed I/O interface, external memory interface, and the PCI/PCI-X bus interface. I/O using SSTL-18 Class I termination standard can achieve up to the stated DDR2 SDRAM interfacing speed with typical DDR2 SDRAM memory interface setup. I/O using general purpose I/O (GPIO) standards such as 3.0, 2.5, 1.8, or 1.5 LVTTTL/LVCMOS are capable of typical 200 MHz interfacing frequency with 10pF load.



Actual achievable frequency depends on design- and system-specific factors. You should perform HSPICE/IBIS simulations based on your specific design and system setup to determine the maximum achievable frequency in your system.

High-Speed I/O Specification

Table 1-53 lists the high-speed I/O timing for Arria II GX devices.

Table 1-53. High-Speed I/O Specifications for Arria II GX Devices (Part 1 of 4)

Symbol	Conditions	I3		C4		C5,I5		C6		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
Clock										
f _{HCLK_IN} (input clock frequency)–Row I/O	Clock boost factor, W = 1 to 40 (1)	5	670	5	670	5	622	5	500	MHz
f _{HCLK_IN} (input clock frequency)–Column I/O	Clock boost factor, W = 1 to 40 (1)	5	500	5	500	5	472.5	5	472.5	MHz
f _{HCLK_OUT} (output clock frequency)–Row I/O	—	5	670	5	670	5	622	5	500	MHz
f _{HCLK_OUT} (output clock frequency)–Column I/O	—	5	500	5	500	5	472.5	5	472.5	MHz

Table 1-63 lists the memory output clock jitter specifications for Arria II GZ devices.

Table 1-63. Memory Output Clock Jitter Specification for Arria II GZ Devices (Note 1), (2), (3)

Parameter	Clock Network	Symbol	-3		-4		Unit
			Min	Max	Min	Max	
Clock period jitter	Regional	$t_{JIT(per)}$	-55	55	-55	55	ps
Cycle-to-cycle period jitter	Regional	$t_{JIT(cc)}$	-110	110	-110	110	ps
Duty cycle jitter	Regional	$t_{JIT(duty)}$	-82.5	82.5	-82.5	82.5	ps
Clock period jitter	Global	$t_{JIT(per)}$	-82.5	82.5	-82.5	82.5	ps
Cycle-to-cycle period jitter	Global	$t_{JIT(cc)}$	-165	165	-165	165	ps
Duty cycle jitter	Global	$t_{JIT(duty)}$	-90	90	-90	90	ps

Notes to Table 1-63:

- (1) The memory output clock jitter measurements are for 200 consecutive clock cycles, as specified in the JEDEC DDR2/DDR3 SDRAM standard.
- (2) The clock jitter specification applies to memory output clock pins generated using differential signal-splitter and DDIO circuits clocked by a PLL output routed on a regional or global clock network as specified. Altera recommends using regional clock networks whenever possible.
- (3) The memory output clock jitter stated in Table 1-63 is applicable when an input jitter of 30 ps is applied.

Duty Cycle Distortion (DCD) Specifications

Table 1-64 lists the worst-case DCD specifications for Arria II GX devices.

Table 1-64. Duty Cycle Distortion on I/O Pins for Arria II GX Devices (Note 1)

Symbol	C4		I3, C5, I5		C6		Unit
	Min	Max	Min	Max	Min	Max	
Output Duty Cycle	45	55	45	55	45	55	%

Note to Table 1-64:

- (1) The DCD specification applies to clock outputs from the PLL, global clock tree, IOE driving dedicated, and general purpose I/O pins.

Table 1-65 lists the worst-case DCD specifications for Arria II GZ devices.

Table 1-65. Duty Cycle Distortion on I/O Pins for Arria II GZ Devices (Note 1)

Symbol	C3, I3		C4, I4		Unit
	Min	Max	Min	Max	
Output Duty Cycle	45	55	45	55	%

Note to Table 1-65:

- (1) The DCD specification applies to clock outputs from the PLL, global clock tree, IOE driving dedicated, and general purpose I/O pins.